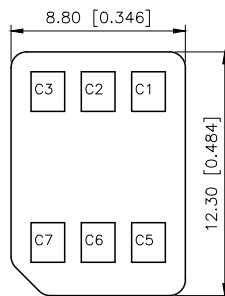
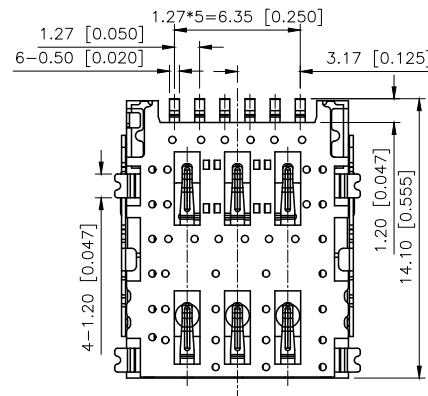
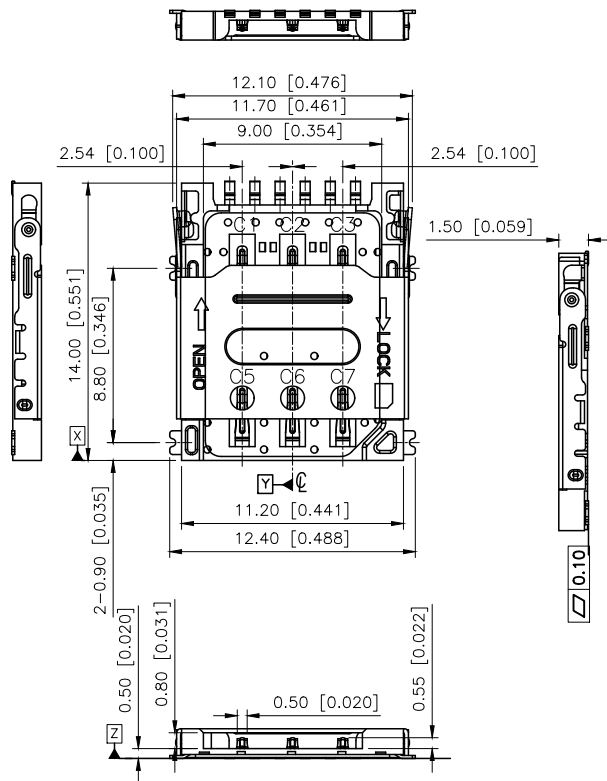
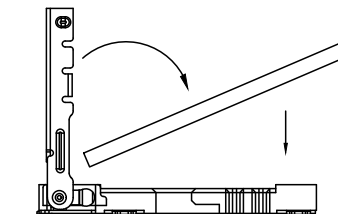


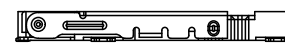
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.08	阿树



NANO SIM CARD



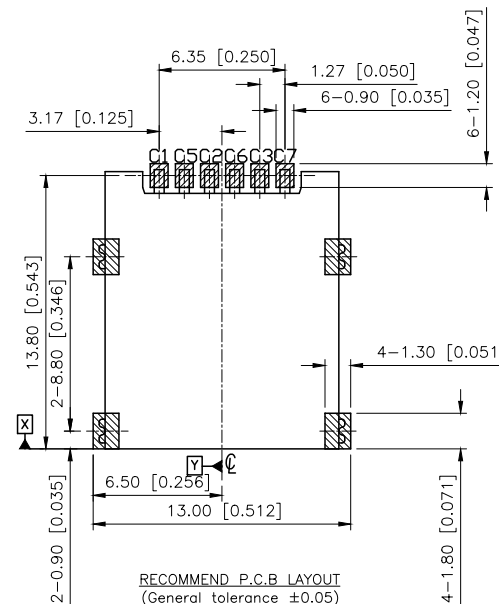
STEP 1 INSERT Nano-SIM CARD



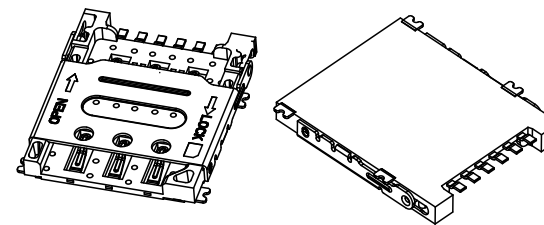
STEP 2 PUSH THE SHELL



STEP 3 FINISH



RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)



3D VIEW

NOTE:

1.材料 Material:

1-1 胶壳 Housing:High Temperature Thermoplastic.
(LCP S475jColor Black UL94V-0

1-2 触点 Contact:Phosphor Branze(C5210R-HT=0.15 $\pm$ 0.02mm)

1-3 盖 Cover:SUS301-HT=0.20 $\pm$ 0.03mm

2.电镀 Plating:

接触端子 Contact terminal:

接触电阻 Contact area: Gold 1u" Min.

焊料区 Solder area: Gold 0.8u" Min

底镀 Underplating: Ni overall 50U"Min,

3.规格 Specification:

3-1.接触电阻 CONTACT RESISTANCE:50 Milliohms Max

3-2.绝缘电阻 INSULATION RESISTANCE:1.000 Megohms Min.

3-3.绝缘耐压 DIELECTRIC WITHSTANDING VOLTAGE:500V AC FOR 1MINUTE.

3-4.工作温度范围 OPERATION TEMPERATURE RANGE:-25C~+700

3-5.耐用性 DURABILITY:3000 CYCLES

4.Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC

5.Part Must Comply Taisol HFWD-3-1-091 Specification.

6.Recommending A Metal More Than 0.15mm Thick.

Please Confirm Solderability,If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
PIN No.	NAME
C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	Vpp
C7	I/O

AuGLAR	$\pm 5^\circ$
X.	± 0.40
X.x	± 0.30
X.xx	± 0.20
X.xxx	± 0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1150
APPROVED		SIZE: A4	DWG NO.: